

## Description

### PECJ P-channel Enhancement Mode Power MOSFET

Features	Application
<ul style="list-style-type: none"> <li><math>V_{DS} = -20V</math>, <math>I_D = -3A</math></li> </ul>	
$R_{DS(ON)} < 70m\Omega$ @ $V_{GS} = -4.5V$	
$R_{DS(ON)} < 100m\Omega$ @ $V_{GS} = -2.5V$	
<ul style="list-style-type: none"> <li>Advanced Trench Technology</li> </ul>	
<ul style="list-style-type: none"> <li>Excellent <math>R_{DS(ON)}</math> and Low Gate Charge</li> </ul>	
<ul style="list-style-type: none"> <li>Lead free product is acquired</li> </ul>	
<b>SOT-23 top view</b>	<b>Marking and pin Assignment</b>
	<b>Schematic Diagram</b>

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
2301C	PECJ2301C	TAPING	SOT-23	7inch	3000	180000

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		-20	V
$V_{GSS}$	Gate-Source Voltage		$\pm 12$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ C$	-3	A
		$T_A = 100^\circ C$	-2	
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		-12	A
$P_D$	Power Dissipation	$T_A = 25^\circ C$	1	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		125	$^\circ C/W$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ C$

## Electrical Characteristics ( $T_J=25^\circ\text{C}$ unless otherwise specified)

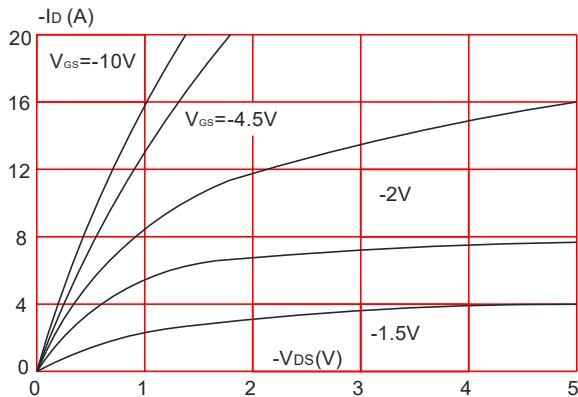
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D = -250\mu\text{A}$	-20	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	-1	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS} = \pm 12\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D = -250\mu\text{A}$	-0.5	-0.7	-1.0	V
$R_{DS(\text{on})}$ note2	Static Drain-Source on-Resistance	$V_{GS} = -4.5\text{V}$ , $I_D = -3\text{A}$	-	55	70	$\text{m}\Omega$
		$V_{GS} = -2.5\text{V}$ , $I_D = -2\text{A}$	-	70	100	
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS} = -10\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	1200	-	pF
$C_{oss}$	Output Capacitance		-	68	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	3.1	-	pF
$Q_g$	Total Gate Charge	$V_{DS} = -10\text{V}$ , $I_D = -2\text{A}$ , $V_{GS} = -4.5\text{V}$	-	4.1	-	nC
$Q_{gs}$	Gate-Source Charge		-	0.8	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	1.1	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}$ , $I_D = -3\text{A}$ , $R_G = 1\Omega$ , $V_{GEN} = -4.5\text{V}$ , $R_L = 1.2\Omega$	-	11	-	ns
$t_r$	Turn-on Rise Time		-	52	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	16	-	ns
$t_f$	Turn-off Fall Time		-	10	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	-3	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-12	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S = -3\text{A}$	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

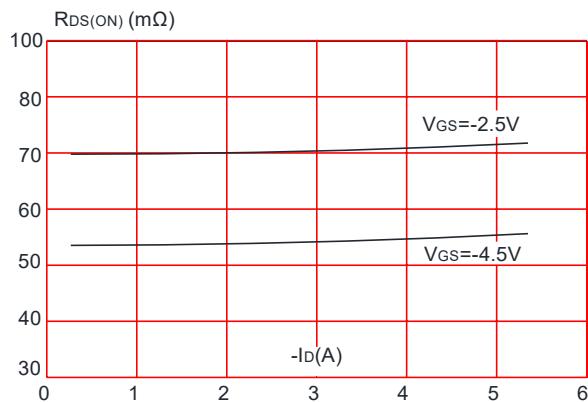
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

## Typical Performance Characteristics

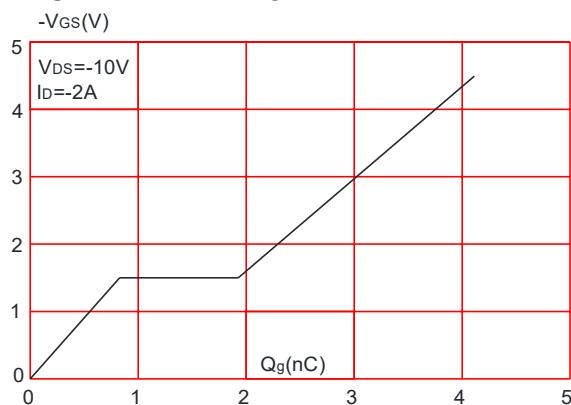
**Figure 1:** Output Characteristics



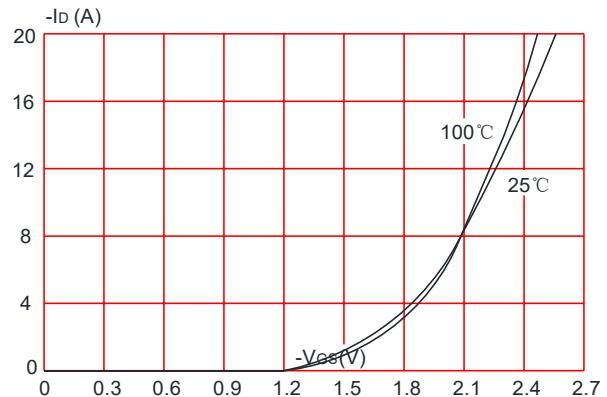
**Figure 3:** On-resistance vs. Drain Current



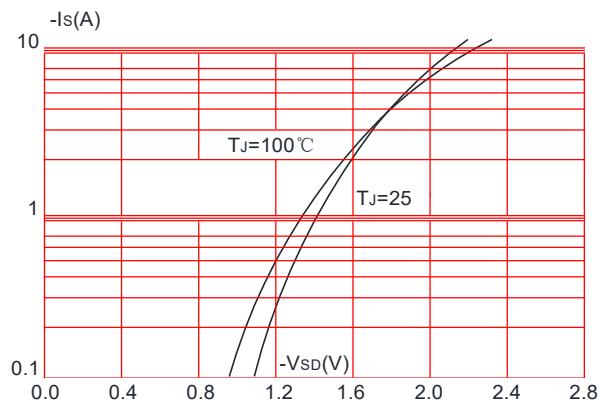
**Figure 5:** Gate Charge Characteristics



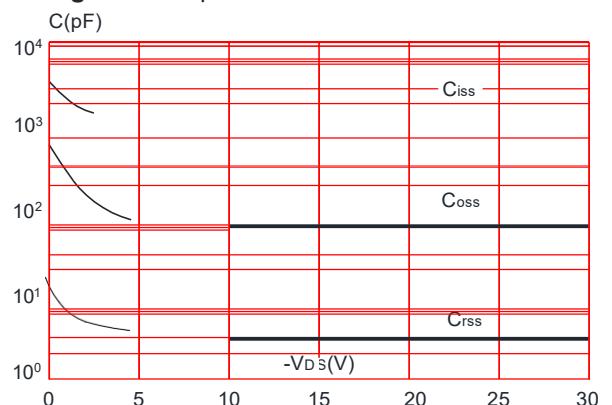
**Figure 2:** Typical Transfer Characteristics



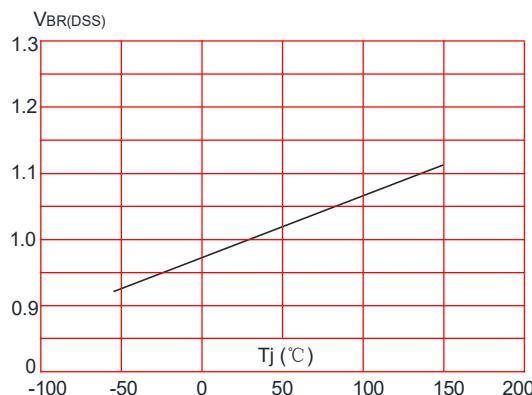
**Figure 4:** Body Diode Characteristics



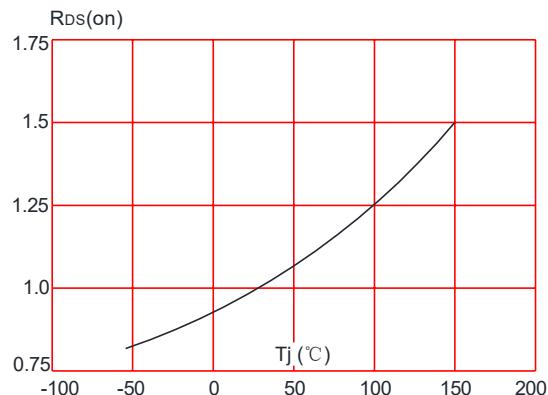
**Figure 6:** Capacitance Characteristics



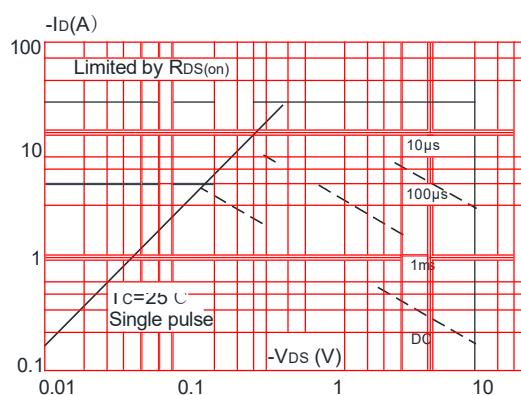
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



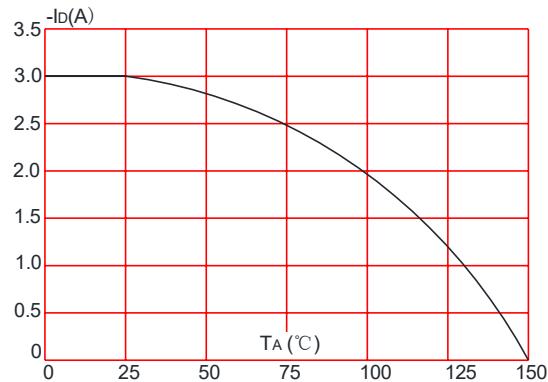
**Figure 8:** Normalized on Resistance vs. Junction Temperature



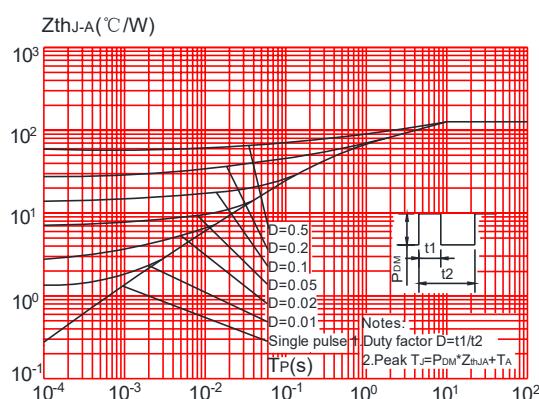
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

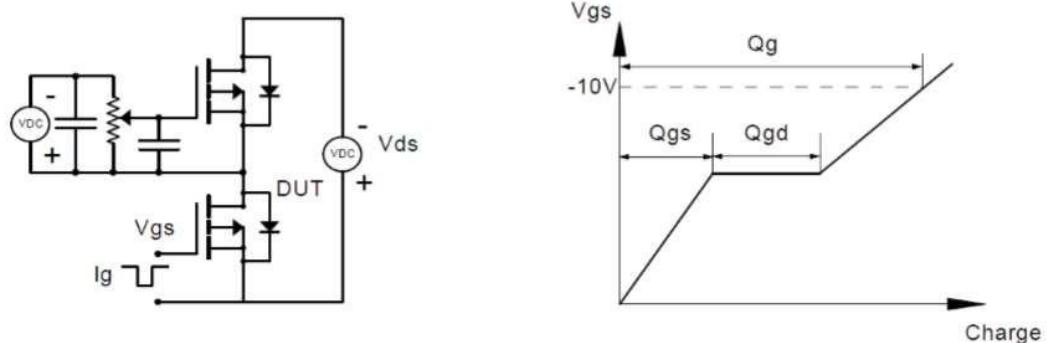


**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

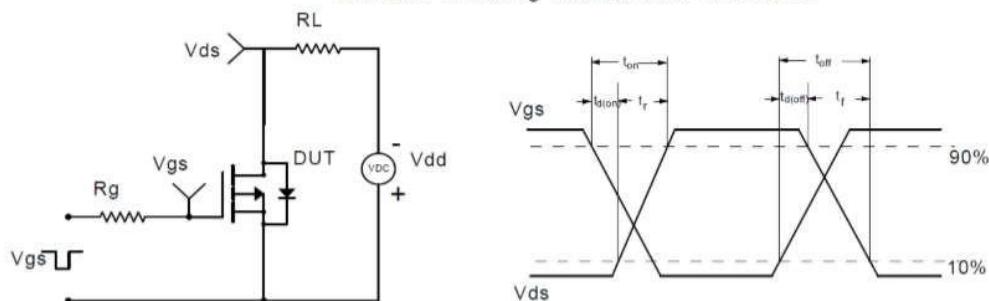


## Test Circuit

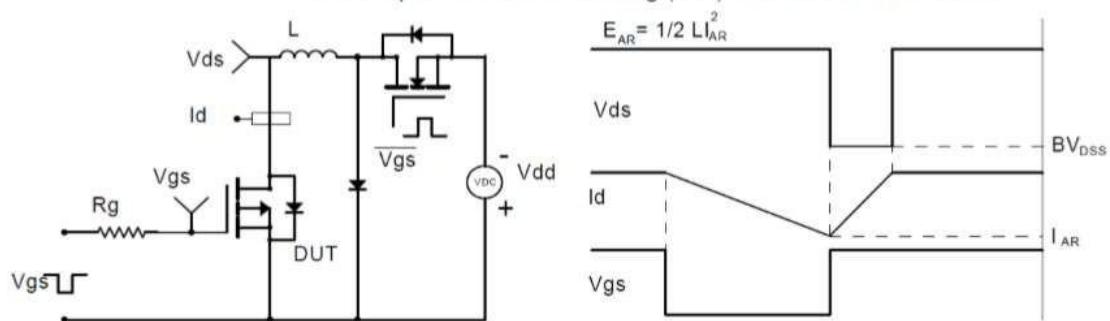
Gate Charge Test Circuit & Waveform



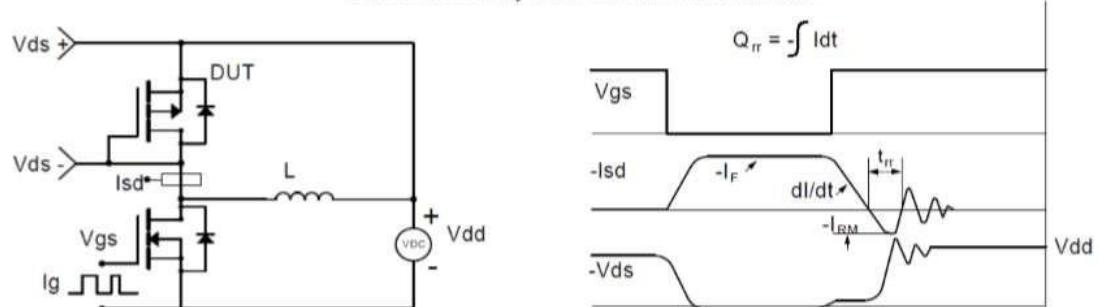
Resistive Switching Test Circuit & Waveforms



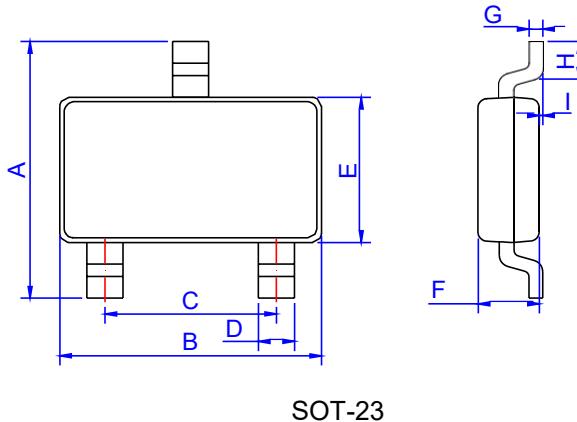
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

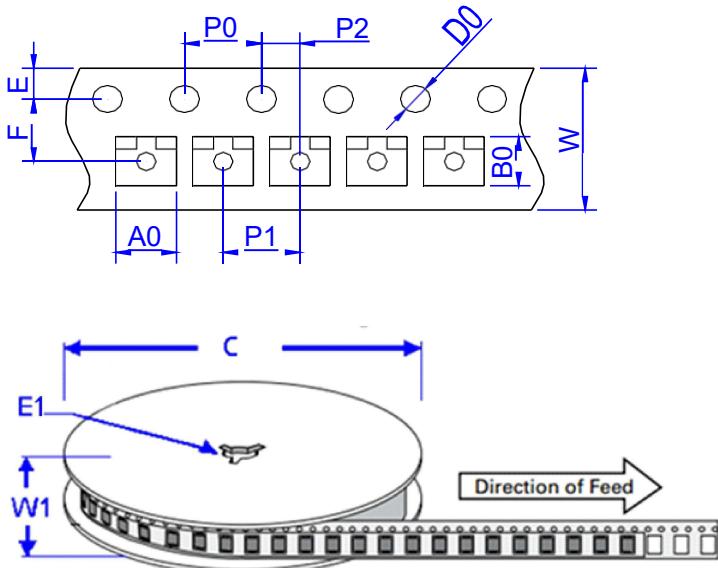


## Package Mechanical Data-SOT-23



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.30	2.40	2.50	0.091	0.095	0.098
B	2.80	2.90	3.00	0.110	0.114	0.118
C	1.90 REF			0.075 REF		
D	0.35	0.40	0.45	0.014	0.016	0.018
E	1.20	1.30	1.40	0.047	0.051	0.055
F	0.90	1.00	1.10	0.035	0.039	0.043
G		0.10	0.15		0.004	0.006
H	0.20			0.008		
I	0		0.10	0		0.004

## Package Information-SOT-23



Ref.	Dimensions	
	Millimeters	Inches
A0	$3.15 \pm 0.3$	$0.124 \pm 0.012$
B0	$2.77 \pm 0.3$	$0.109 \pm 0.012$
C	178	7.0
D0	$1.50 \pm 0.1$	$0.059 \pm 0.004$
E	$1.75 \pm 0.2$	$0.069 \pm 0.008$
E1	$13.3 \pm 0.3$	$0.524 \pm 0.012$
F	$3.5 \pm 0.2$	$0.138 \pm 0.008$
P0	$4.00 \pm 0.2$	$0.157 \pm 0.008$
P1	$4.00 \pm 0.2$	$0.157 \pm 0.008$
P2	$2.00 \pm 0.2$	$0.079 \pm 0.008$
W	$8.00 \pm 0.2$	$0.315 \pm 0.008$
W1	$11.5 \pm 1.0$	$0.453 \pm 0.039$